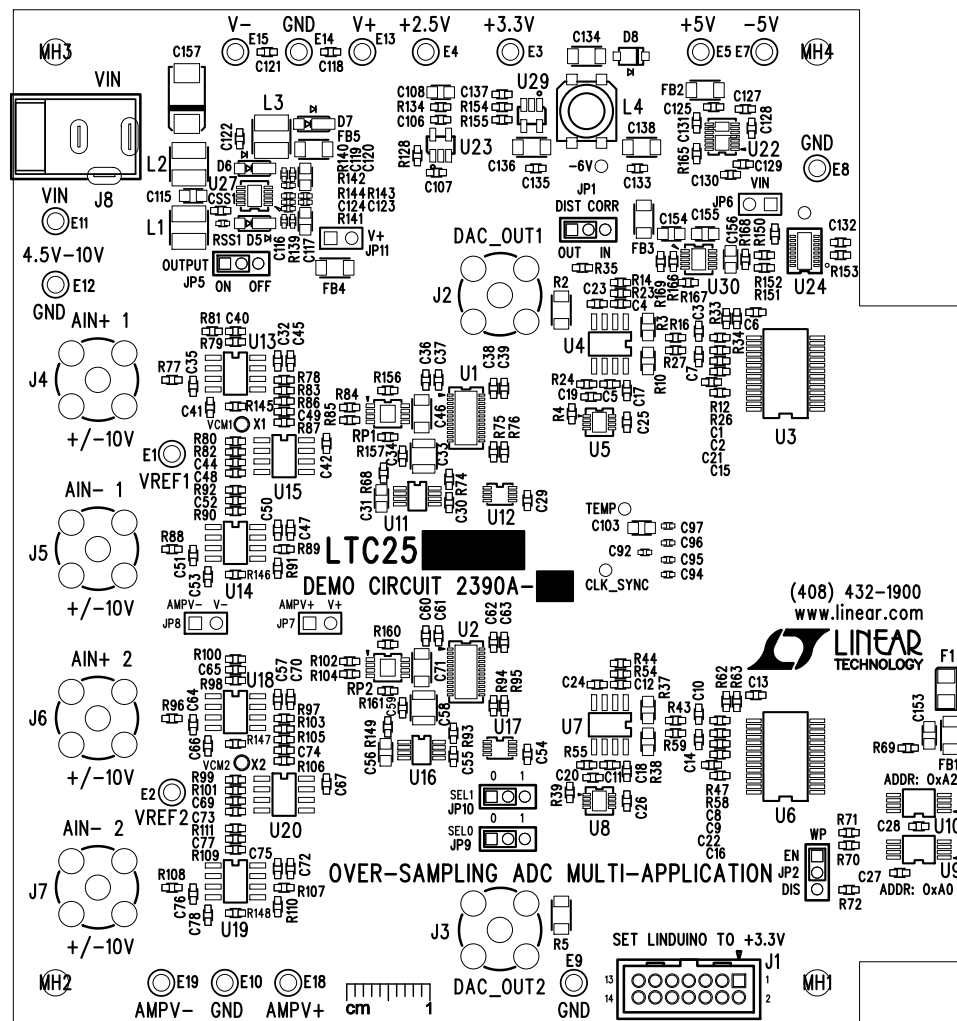
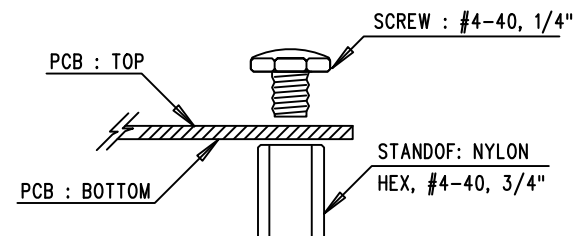


REVISION HISTORY			
ECO	REV	DESCRIPTION	APP. ENG.
-	4	PRODUCTION	MARK T.
			DATE
			08-30-16




NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL MH1-MH4 AS SHOWN BELOW:



8. MARK EACH ASSEMBLY TYPE, SUFFIX IN THE WHITE BLOCK AREA WITH BLACK PERMANENT MARKER AS SHOWN IN TABLE BELOW:

ASSY	U1,U2	SUFFIX
-A	LTC2500-32	00-32
-B	TBD	TBD

APPROVALS		 <div> 1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1900 www.linear.com LTC CONFIDENTIAL- FOR CUSTOMER USE ONLY </div>	
PCB DES.	KIM T.		
APP ENG.	MARK T.	TITLE: TOP ASSEMBLY DRAWING	
		OVER-SAMPLING ADC MULTI-APPLICATION	
		SIZE	IC NO.
		N/A	LTC25XXIDKD FAMILY
		REV.	
		4	
SCALE = NONE		FILENAME:	SHT 1 OF 2
		DC2390A-4.PCB	